

STF5N80K5

N-channel 800 V, 1.50 Ω typ., 4 A MDmesh™ K5 Power MOSFET in a TO-220FP package

Datasheet - production data

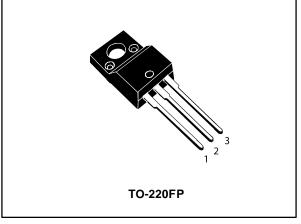
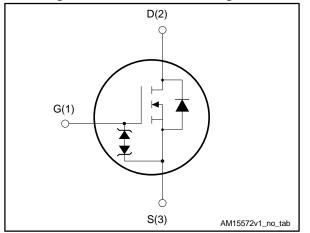


Figure 1: Internal schematic diagram



Features

Order code	VDS	R _{DS(on)} max.	ID	
STF5N80K5	800 V	1.75 Ω	4 A	

- Industry's lowest R_{DS(on)} x area
- Industry's best FoM (figure of merit)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

• Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh[™] K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Table 1: Device summary

Order code	Marking	Package	Packing
STF5N80K5	5N80K5	TO-220FP	Tube

DocID028509 Rev 3

This is information on a product in full production.

Contents

Contents

1	Electric	al ratings	3
2	Electric	al characteristics	4
	2.1	Electrical characteristics (curves)	6
3	Test cir	cuits	8
4	Packag	e information	9
	4.1	TO-220FP package information	10
5	Revisio	n history	12



1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
Vgs	Gate-source voltage	± 30	V
ID	Drain current (continuous) at T_C = 25 °C	4	А
ΙD	Drain current (continuous) at T _c = 100 °C	2.3	А
ID ⁽¹⁾	Drain current (pulsed)	16	А
P _{TOT}	Total dissipation at $T_c = 25 \text{ °C}$	20	W
dv/dt (2)	Peak diode recovery voltage slope	4.5	
dv/dt ⁽³⁾	MOSFET dv/dt ruggedness	50	V/ns
Viso	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1 s; T_c= 25 °C)	2500	V
Tj	Operating junction temperature range	- 55 to	℃
T _{stg}	Storage temperature range	150	C

Notes:

 $^{(1)}\mbox{Pulse}$ width limited by safe operating area

 $^{(2)}I_{SD}$ \leq 4 A, di/dt =100 A/µs; V_Ds peak < V(_BR)DSS, V_DD = 640 V $^{(3)}V_{DS}$ \leq 640 V

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	6.25	°C/W
R _{thj-amb}	Thermal resistance junction-ambient	62.5	°C/W

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by Tjmax)		А
Eas	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$, $V_{DD} = 50$ V)	165	mJ



2 Electrical characteristics

 $T_C = 25$ °C unless otherwise specified

Table 5: On/off-state							
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
V(BR)DSS	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	800			V	
		$V_{GS} = 0 V, V_{DS} = 800 V$			1	μA	
IDSS	Zero gate voltage drain current	$V_{GS} = 0 V, V_{DS} = 800 V$ T _c = 125 °C ⁽¹⁾			50	μA	
I _{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±10	μA	
V _{GS(th)}	Gate threshold voltage	$V_{DD} = V_{GS}$, $I_D = 100 \ \mu A$	3	4	5	V	
R _{DS(on)}	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 2 A		1.50	1.75	Ω	

Table 5: On/off-state

Notes:

⁽¹⁾Defined by design, not subject to production test

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Cymbol	T diameter	rest conditions		· yp.	max.	Unit
Ciss	Input capacitance		-	177	-	pF
Coss	Output capacitance	V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0 V	-	15	-	pF
Crss	Reverse transfer capacitance		-	0.3	-	pF
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	V _{DS} = 0 to 640 V, V _{GS} = 0 V	-	33	-	pf
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related	$v_{\rm DS} = 0.10.040 v, v_{\rm GS} = 0.0$	-	12	-	pf
Rg	Intrinsic gate resistance	f = 1 MHz , I _D = 0 A	-	16	-	Ω
Qg	Total gate charge	$V_{DD} = 640 \text{ V}, \text{ I}_{D} = 4 \text{ A}$	-	5	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 10 V	-	1.7	-	nC
Q _{gd}	Gate-drain charge	see Figure 15: "Test circuit for gate charge behavior"	-	2.9	-	nC

Table 6: Dynamic

Notes:

 $^{(1)}C_{0(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

 $^{(2)}C_{0(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .



Electrical characteristics

Table 7: Switching times							
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
t _{d(on)}	Turn-on delay time	$V_{DD}\text{=}\;400\;V,I_{D}=2\;A,R_{G}\text{=}\;4.7\;\Omega$	-	12.7	-	ns	
tr	Rise time	V _{GS} = 10 V	-	11.7	-	ns	
t _{d(off)}	Turn-off delay time	see Figure 14: "Test circuit for resistive load switching times" and Figure 19: "Switching time waveform"	-	23	-	ns	
t _f	Fall time		-	14.8	-	ns	

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Isd	Source-drain current		-		4	А
Isdm ⁽¹⁾	Source-drain current (pulsed)		-		16	А
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 4 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$	-		1.6	V
t _{rr}	Reverse recovery time	$I_{SD} = 4 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	265		ns
Qrr	Reverrse recovery charge	V _{DD} = 60 V see <i>Figure 16: "Test circuit</i>	-	1.59		μC
IRRM	Reverse recovery current	for inductive load switching and diode recovery times"	-	12		А
trr	Reverse recovery time	$I_{SD} = 4 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	386		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}, \text{ T}_{j} = 150 ^{\circ}\text{C}$ see Figure 16: "Test circuit for inductive load switching and diode recovery times"	-	2.18		μC
Irrm	Reverse recovery current		-	11.3		A

Notes:

⁽¹⁾Pulse width limited by safe operating area

 $^{(2)}\text{Pulsed:}$ pulse duration = 300 $\mu\text{s},$ duty cycle 1.5%

Table 9: Gate-source Zener diode

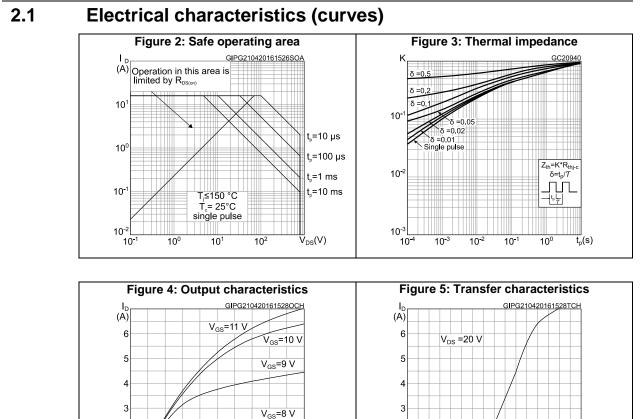
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _(BR) GSO	Gate-source breakdown voltage	I _{GS} = ± 1mA, I _D = 0 A	30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.



2

0



V_{GS}=7 V V_{GS}=6 V

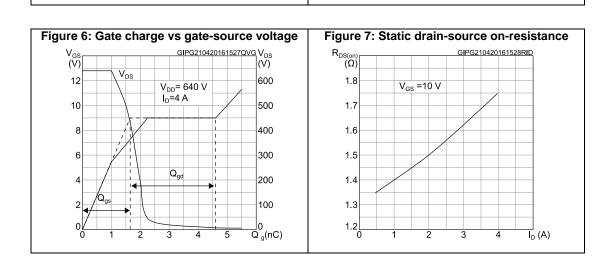
16

V_{DS} (V)

12

8

4



0

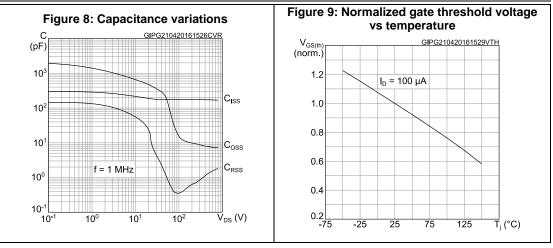
4 5 6

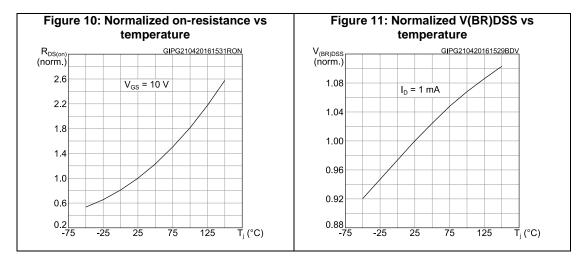
8 9 10 11

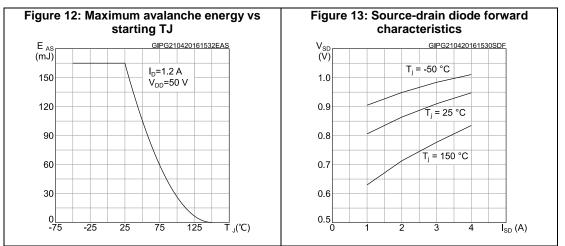


V_{GS} (V)

Electrical characteristics



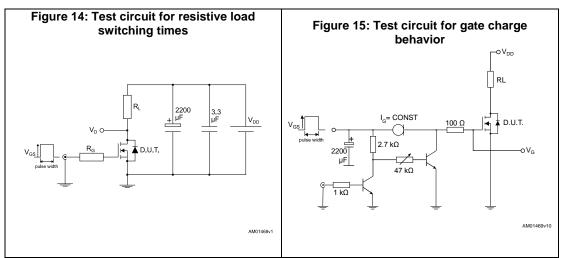


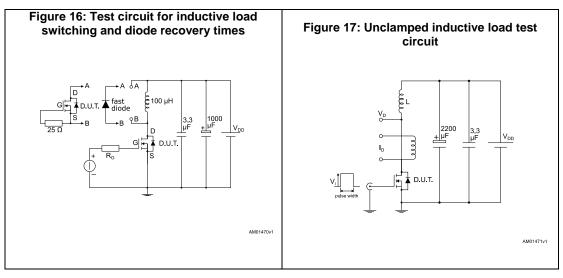


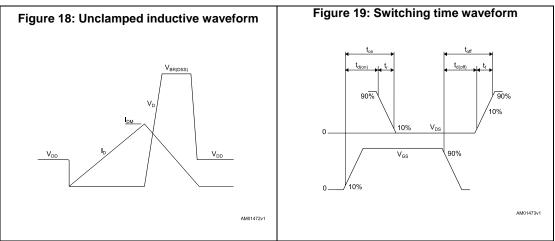
57

DocID028509 Rev 3

3 Test circuits







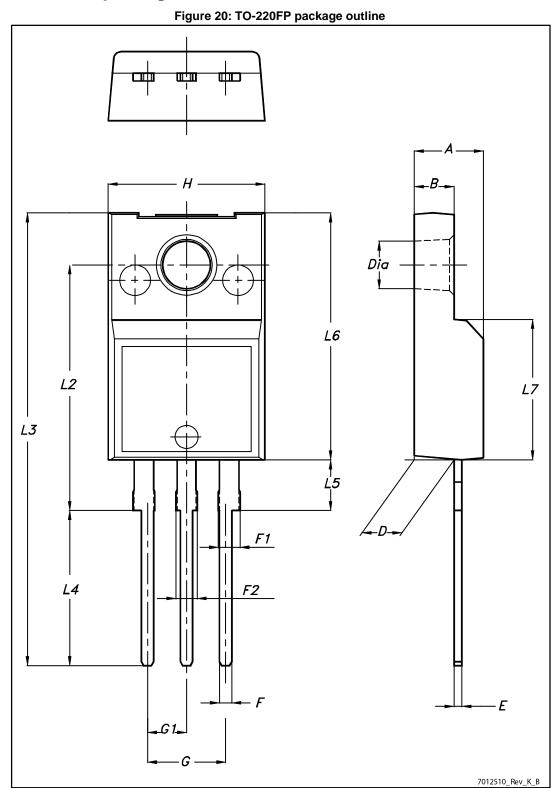


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.









DocID028509 Rev 3

STF5N80K5

(5			Package information
	Table 10: TO-220FP pa	ackage mechanical data	
Dim.		mm	
Dim.	Min.	Тур.	Max.
A	4.4		4.6
В	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
Н	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2



Revision history 5

Table 11: Document revision history

Date	Revision	Changes
16-Oct-2015	1	First release.
06-Nov-2015	2	Updated title in cover page.
09-May-2016	3	Modified: title Table 2: "Absolute maximum ratings", Table 3: "Thermal data", Table 5: "On/off-state", Table 6: "Dynamic", Table 7: "Switching times", Table 8: "Source-drain diode" Added: Section 3.1: "Electrical characteristics (curves)" Modified: Section 4: "Test circuits" Minor text changes





STF5N80K5

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics - All rights reserved



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by STMicroelectronics manufacturer:

Other Similar products are found below :

614233C 648584F IRFD120 JANTX2N5237 2N7000 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2911 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B